

## Abstract

A novel board for printed wiring comprising a fine conductor wiring having a clear and favorable boundary line and fabricated by an ordinal printing method such as screen printing, a printed wiring board using the same, and methods for manufacturing them. A board for printed wiring and a method for manufacturing the same are characterized in that the surface of a board is subjected to one of the surface treatments: (a) roughening, (2) plasma treatment, (3) roughening and then plasma treatment, and (4) roughening and then forming of a metal film coating by sputtering. A printed wiring board and a method for manufacturing the same is characterize in that a conductor wiring is fabricated by printing using a conductive paste containing metal particles the average particle diameter of which is  $4\text{ }\mu\text{m}$  or less and the maximum particle diameter of which is  $15\text{ }\mu\text{m}$  or less. Another printed wiring board and a method for manufacturing the same is characterized in that the surface of a conductor wiring fabricated using a conductive paste containing metal particles M and a binder B at a volume ratio of M/B of 1/1 to 1.9/1 is etched, a plating coating is formed on the surface.